

Electronic Acknowledgement Receipt

EFS ID:	1032364
Application Number:	10826713
Confirmation Number:	2185
Title of Invention:	Wafer-level assembly method for chip-size devices having flipped chips
First Named Inventor:	William D. Boyd
Customer Number:	23494
Filer:	Yingsheng Tung/Jackie McBride
Filer Authorized By:	Yingsheng Tung
Attorney Docket Number:	TI-37214
Receipt Date:	27-APR-2006
Filing Date:	16-APR-2004
Time Stamp:	10:50:29
Application Type:	Utility
International Application Number:	

Payment information:

Submitted with Payment	no
------------------------	----

File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Response to Election / Restriction Filed	TI-37214_ELECTION.pdf	2901	no	1

Warnings:	
Information:	
Total Files Size (in bytes):	2901
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p>	